

## NC676 Solder Paste

Alloy: **63/37 Type 3** Metal Loading: **89.5%**  
QC/Lot#: **23826** Mfg Date: **7/18/2012**

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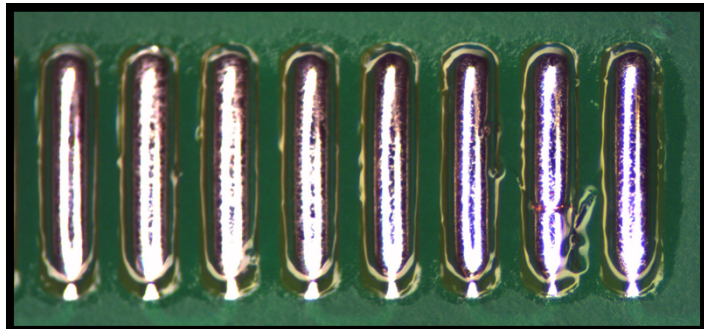
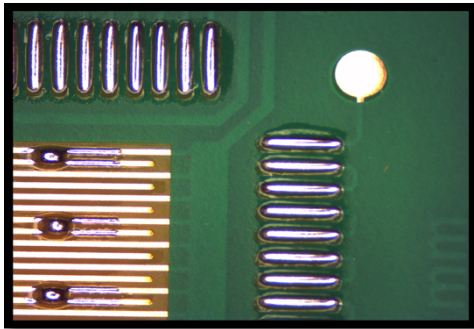
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### Summary

Leaded paste that is no clean, pin probable and halogen free. Attributes compared to the other products that were tested are below:

- \* Minimal Graping
- \* Low slump with low viscosity
- \* Excellent wetting
- \* Great open time with tack life over 72 hours
- \* Fantastic Cosmetics

### Cosmetics





**Standards Tests**

**NC676 Solder Paste**

**Metal Loading**

Metal 89.4%

**Viscosity**

Brookfield 625 Kcps  
Malcom 130 Pa·s

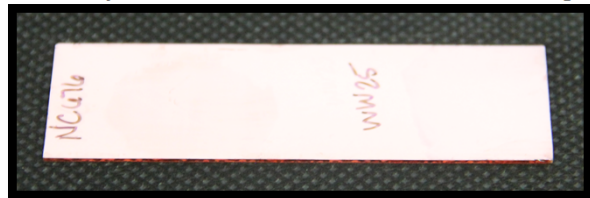
**Silver Chromate**

Pass



**Copper Mirror**

Pass (No evidence of mirror breakthrough)



**IPC Classification**

ROLO

**Flouride**

Pass



**Tack Testing**

0 Hours	24 Hours	48 Hours	72 Hours	96 Hours
104.48	111.12	112.02	115.28	80.68

**SIR**

Pass

**Electromigration**

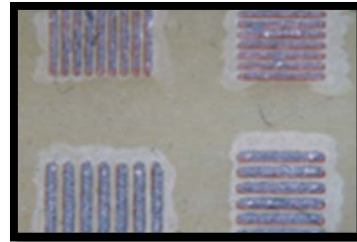
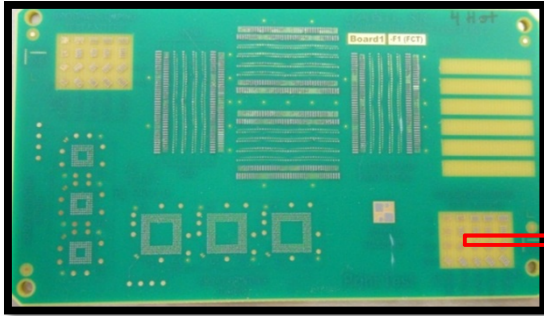
Pass





**Cold Slump**

**NC676 Solder Paste**



**Cold Slump**

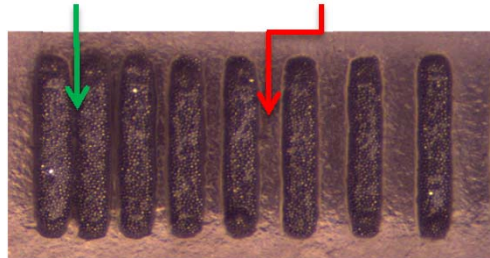
**IPC Slump Results**

**Bridging Quantity**

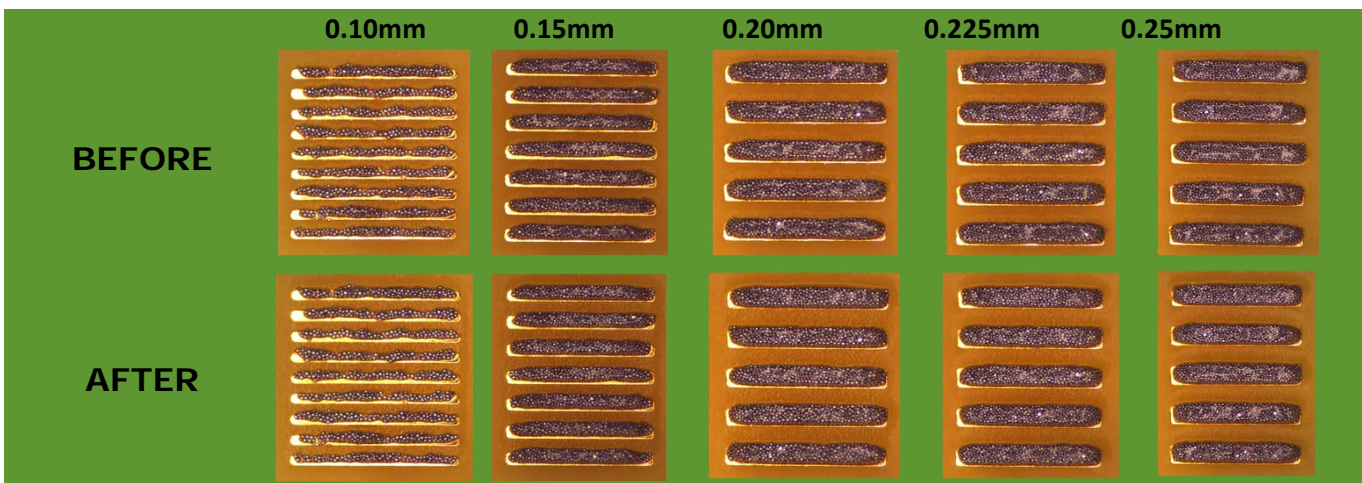
Pad	Defect Count
0.10mm	0
0.15mm	0
0.20mm	0
0.225mm	0
0.25mm	0

**Cold Slump 0.06**  
**Passing Result**

25C slump fail  
limit (0.25mm)



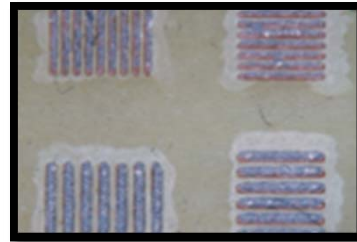
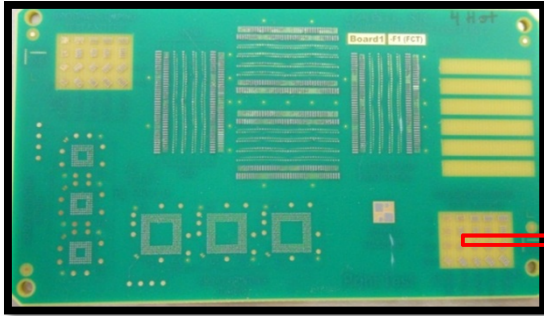
**Cold Slump Test Board**





**Hot Slump**

**NC676 Solder Paste**



**Hot Slump**

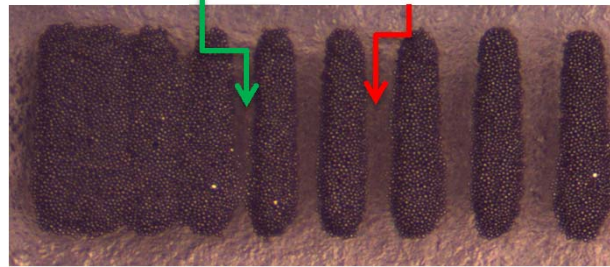
**IPC Slump Results**

**Bridging Quantity**

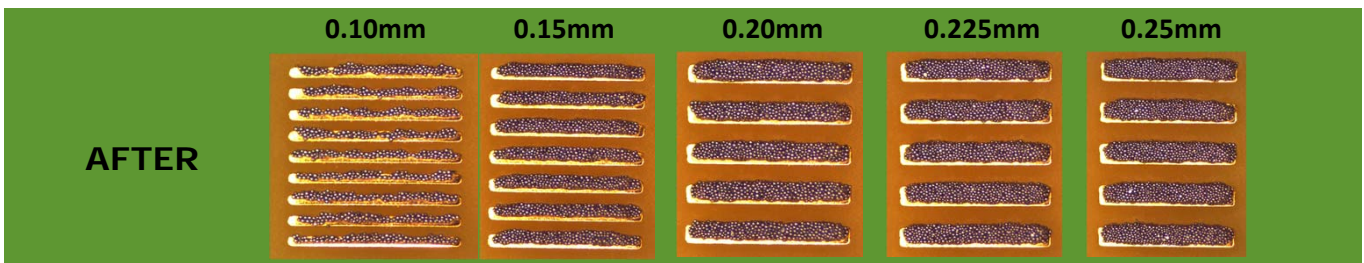
Pad	Defect Count
0.10mm	0
0.15mm	0
0.20mm	0
0.225mm	0
0.25mm	0

Hot Slump 0.20  
**Passing Result**

150C slump fail  
limit (0.30mm)

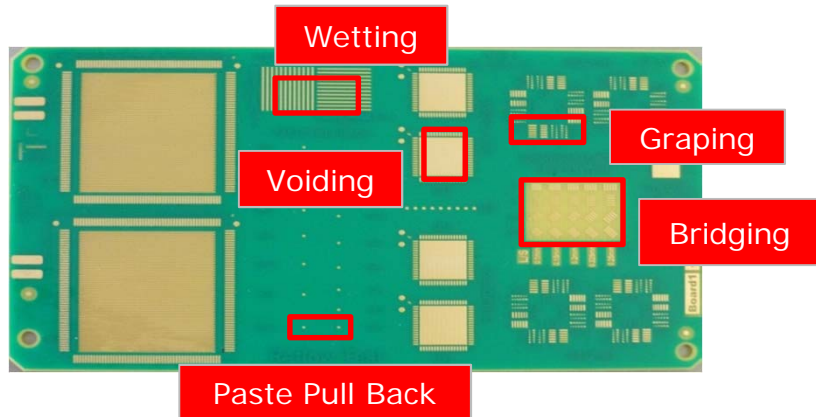


**Hot Slump Test Board**





# Inspection Area Overview

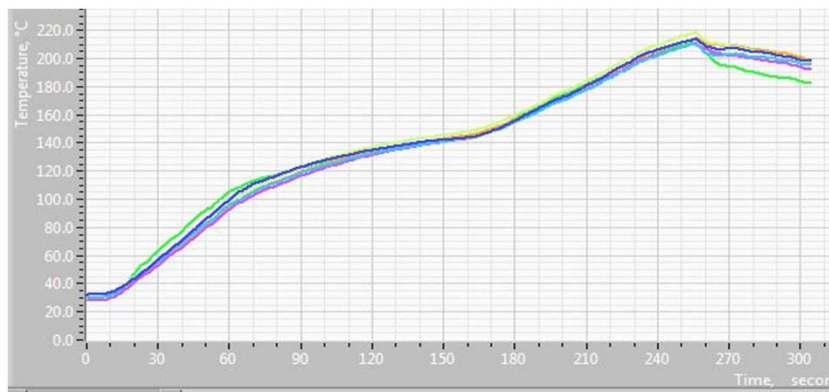


## High Curve

## Low Curve

N/A for Leaded Paste

## Optimal Curve





**Reflow Data (Graping)**

**NC676 Solder Paste**

**Graping Inspection**

Measure the performance of graping on 96 pads with 1/2 being mask defined. Pad size varies from 7X7 mil to 12X12 mil . When counting the pads we identified the largest feature pad that showed the graping effect then counted all pads at this size and smaller. These are recorded in the tables below. Pads were on four different locations of the board.

**High**

CRD	Brd 1	Brd 2	Brd 3	Brd 4	Total
G1	<b>N/A for Leaded Paste</b>				
G7					
G10					
G15					

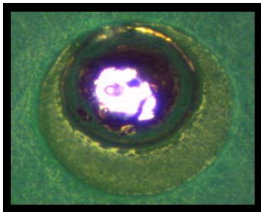
Graping Comparison	
Product	Total Grapes
NC676	32
Competitor A	24
Competitor B	61

**Low**

CRD	Brd 1	Brd 2	Brd 3	Brd 4	Total
G1	<b>N/A for Leaded Paste</b>				
G7					
G10					
G15					

**Optimal**

CRD	Brd 1	Brd 2	Brd 3	Brd 4	Total
G1	4	2	1	1	8
G7	5	3	2	0	10
G10	4	2	0	2	8
G15	3	3	0	0	6



**Reflow Data (Wetting)**
**NC676 Solder Paste**
**Wetting/Spread Inspection Test**

In each of the wetting/spread areas we identified the number of lines that had one or more bridge of the solder bricks. The maximum number of lines is 24. We then measure the most bricks that were bridged in one line. These results are shown below.

**High**

Board	Total Lines	Most on 1
1	N/A for Leaded Paste	
2		
3		
4		
Total		

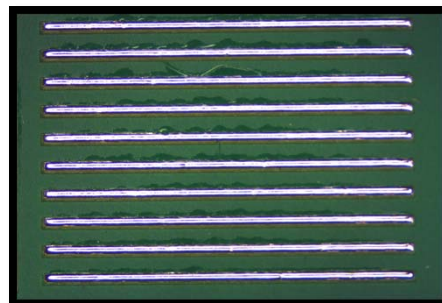
Wetting Comparison		
Product	Total	Most
NC676	24	15
Competitor A	24	15
Competitor B	24	15

**Low**

Board	Total Lines	Most on 1
1	N/A for Leaded Paste	
2		
3		
4		
Total		

**Optimal**

Board	Total Lines	Most on 1
1	24 out of 24	15 out of 15
2	24 out of 24	15 out of 15
3	24 out of 24	15 out of 15
4	24 out of 24	15 out of 15
Total	96 out of 96	60 out of 60





**Reflow Data (Solder Ball)**

**NC676 Solder Paste**

**Paste Pullback (Solder Ball)**

Measure the performance by volume of the solder paste to pullback on a pad. The start of the volume was at 500% with the maximum being 1250%. Any solder ball that was found not coalescing with the rest of the solder was failed.

**High**

Board	Pad Size
1	
2	
3	
4	
Average	

N/A for Leaded Paste

Paste Pullback Comparison	
Product	Average
NC676	1150%
Competitor A	950%
Competitor B	1225%

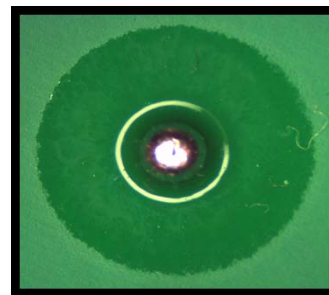
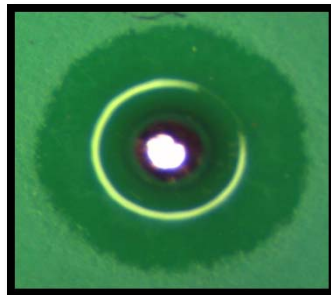
**Low**

Board	Pad Size
1	
2	
3	
4	
Average	

N/A for Leaded Paste

**Optimal**

Board	Pad Size
1	1225%
2	1225%
3	1225%
4	925%
Average	1150%







**Reflow Data (Bridging)**

**NC676 Solder Paste**

**Bridging Inspection**

We measured the number of bridge occurrences and recorded in the tables below. We should note that the .1m m pads had minimal paste release which led to 0 bridges. Thus this pad offered no value in this study.

**High**

Board	Defect Count
1	N/A for Leaded Paste
2	
3	
5	
Total	

**Low**

Board	Defect Count
1	N/A for Leaded Paste
2	
3	
4	
Total	

**Optimal**

Board	Defect Count
1	0
2	4
3	0
4	5
Total	9

